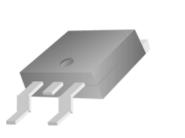
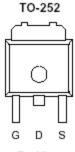
## N-Channel 30-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$r_{DS(on)} m(\Omega)$	<b>I</b> <sub>D</sub> (A)		
30	$59 @ V_{GS} = 10V$	24		
	$88 @ V_{GS} = 4.5V$	20		

- Low r<sub>DS(on)</sub> provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe DPAK saves board space
- Fast switching speed
- High performance trench technology





Top View

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)					
Parameter			Limit	Units	
Drain-Source Voltage			30	V	
Gate-Source Voltage			±20	V	
Continuous Drain Current <sup>a</sup>	T <sub>C</sub> =25°C	$I_{\mathrm{D}}$	24	Α	
Pulsed Drain Current <sup>b</sup>			75	А	
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	30	A		
Power Dissipation <sup>a</sup>	T <sub>C</sub> =25°C	$P_{\mathrm{D}}$	50	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Maximum	Units	
Maximum Junction-to-Ambient <sup>a</sup>	$R_{ heta JA}$	50	°C/W	
Maximum Junction-to-Case	$R_{ heta JC}$	3.0	°C/W	

1

### Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

Danamakan	Carrack - 1	Symbol Test Conditions		Limits	5	TT	
Parameter	Symbol			Тур	Max	Unit	
Static							
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \text{ uA}$	1		2.3	V	
Gate-Body Leakage	Igss	$V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	A	
Zeio Gate Voltage Diain Current	IDSS	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			25	uA	
On-State Drain Current <sup>A</sup>	ID(on)	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	34			A	
D : C O D : A		$V_{GS} = 10 \text{ V}, I_{D} = 12 \text{ A}$			59		
Drain-Source On-Resistance <sup>A</sup>	fDS(on)	$V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$			88	mΩ	
Forward Tranconductance <sup>A</sup>	gs	$V_{DS} = 15 \text{ V}, I_D = 12 \text{ A}$		22		S	
Diode Forward Voltage	V <sub>SD</sub>	$I_S = 24 \text{ A}, V_{GS} = 0 \text{ V}$		1.1		V	
Dynamic <sup>b</sup>							
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V},$ $I_D = 10 \text{ A}$		2.2		nC	
Gate-Source Charge	$Q_{gs}$			0.5			
Gate-Drain Charge	$Q_{gd}$			0.8			
Input Capacitance	Ciss	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1MHz		720		pF	
Output Capacitance	Coss			165			
Reverse Transfer Capacitance	Crss			60			
Turn-On Delay Time	t <sub>d(on)</sub>			16			
Rise Time	$t_{\rm r}$	$V_{\rm DD} = 25 \ V, R_{\rm L} = 25 \ \Omega \ , {\rm Id} = 24 \ A,$ $V_{\rm GEN} = 10 \ V$		5		nS	
Turn-Off Delay Time	t <sub>d(off)</sub>			23			
Fall-Time	tf			3			

#### Notes

- a. Pulse test:  $PW \le 300us duty cycle \le 2\%$ .
- b. Guaranteed by design, not subject to production testing.

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# Typical Electrical Characteristics (N-Channel)

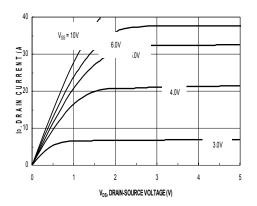


Figure 1. On-Region Characteristics

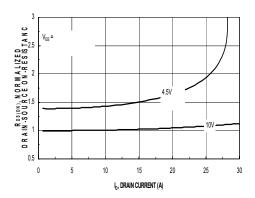


Figure 3. On Resistance Vs Vgs Voltage

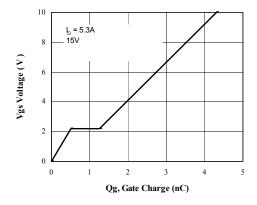


Figure 5. Gate Charge Characteristics

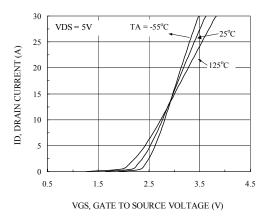


Figure 2. Body Diode Forward Voltage Variation with Source Current and Temperature

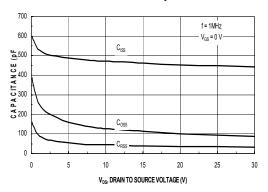


Figure 4. Capacitance Characteristics

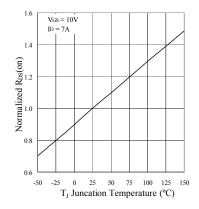


Figure 6. On-Resistance Variation with Temperature

## Typical Electrical Characteristics (N-Channel)

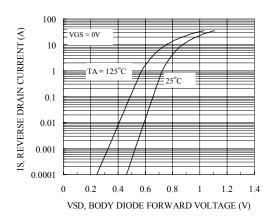


Figure 7. Transfer Characteristics

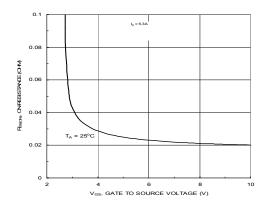


Figure 8. On-Resistance with Gate to Source Voltage

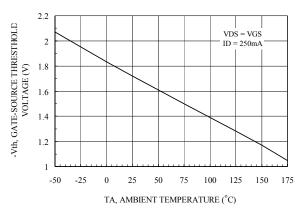


Figure 9. Vth Gate to Source Voltage Vs Temperature

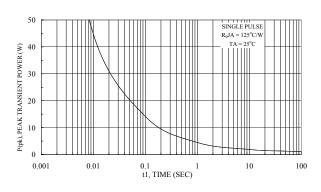
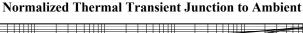


Figure 10. Single Pulse Maximum Power Dissipation



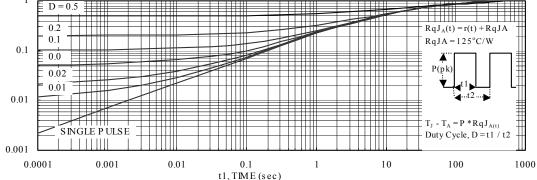
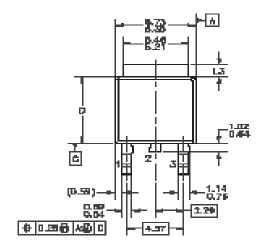
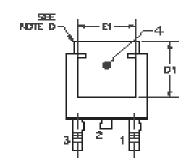
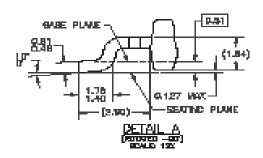


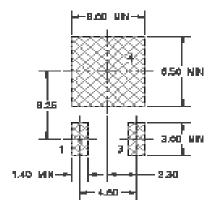
Figure 11. Transient Thermal Response Curve

# Package Information

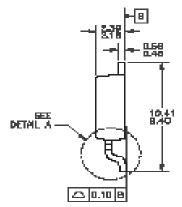








LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

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